

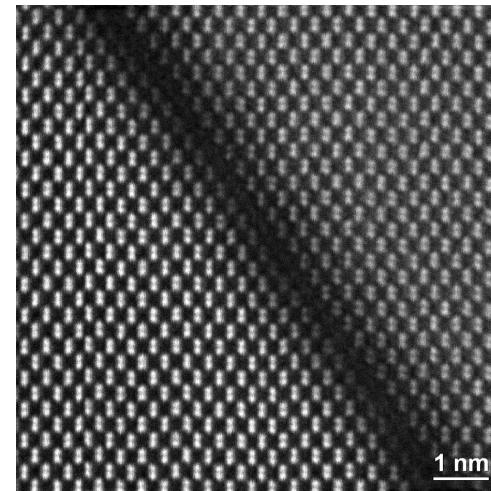
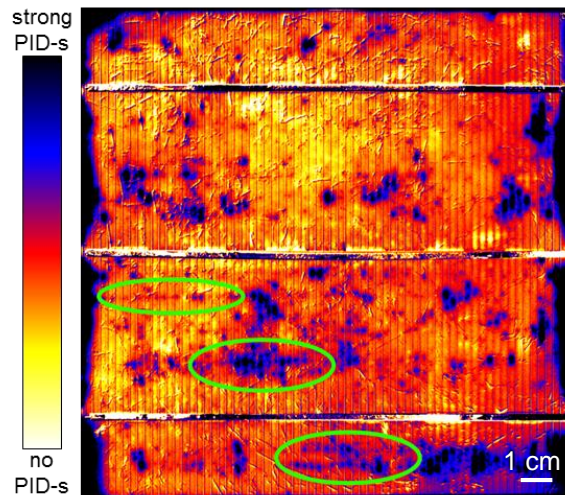
Origin of PID-s



Volker Naumann¹, Otwin Breitenstein², Jan Bauer², Christian Hagendorf¹

¹ Fraunhofer Center for Silicon Photovoltaics CSP, Halle, Germany

² Max Planck Institute of Microstructure Physics, Halle, Germany



Background

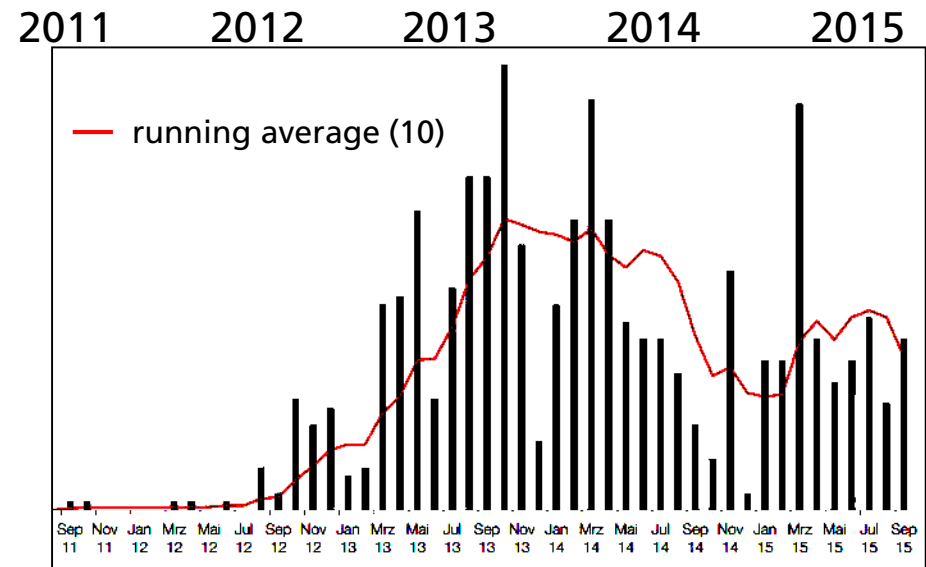
PID is still in the field



- Potential induced degradation (PID) of solar modules leads to yield losses
- Counter-measures against PID known since a few years, **but costly**
- PID 'of the shunting type' of c-Si PV modules (PID-s) is an ongoing issue!



PV power plants with confirmed cases of PID in Europe ^[1]



Frequency of new complaints in Europe by month ^[2]

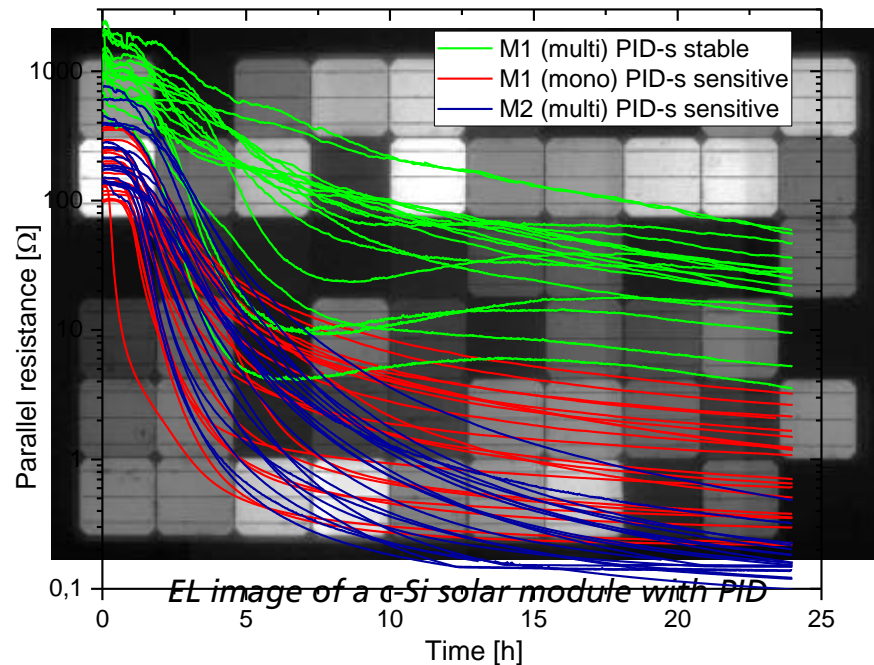
[1] C. Hinz et al., PADCON PID Workshop, 10.11.2015, http://padcon.de/content/site/dateien/2620Vergleich_von_unterschiedlichen_Regenerationsmethoden_fuer_PID.pdf

[2] Benjamin Sandrock et al., PADCON PID Workshop, 08.04.2016, http://padcon.de/content/site/dateien/2733Suncycle_PID_Sicher_erkennen_und_erfolgreich_heilen.pdf

Motivation

Variation of PID-s susceptibility

- Variation of PID-shunting (PID-s) sensitivity of individual cells:
 - On module level: "checkerboard pattern"
 - On cell level: fluctuation of $R_{\text{shunt}}(t)$ of 'similar' cells



'PIDcon'

- Reason for variation?
- Inherent stability against PID-s?

Aim of this talk:

- Initial defects of PID-shunts

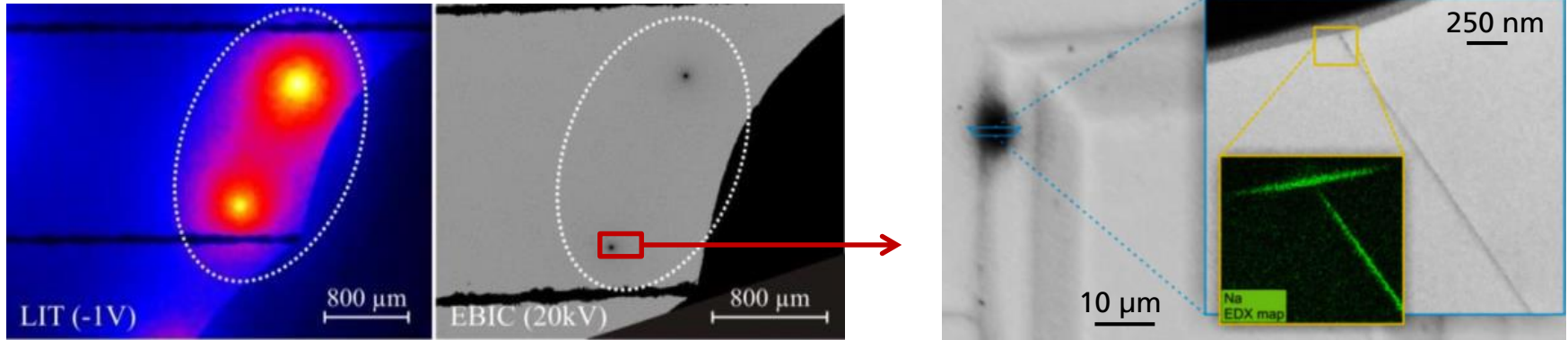
Outline



- PID-s root cause analysis
 - Type of stacking faults
- Quest for PID-s defect precursors
 - 1) Primordial stacking faults
 - 2) Threading dislocations
 - 3) Surface defects
- Conclusion

PID-s root cause analysis

Results in a nut-shell



- Local hot spots on degraded cells [1]
- PID-shunting ('PID-s') of p-n junction by Na-decorated stacking faults [2]*
- Out-diffusion of Na during recovery [3]
- Na-decoration even found after corona test [4]

[1] V. Naumann et al., Microstructural Analysis of Crystal Defects Leading to Potential-Induced Degradation (PID) of Si Solar Cells, Energy Procedia 33, 76 (2013).

[2] V. Naumann et al., Explanation of potential-induced degradation of the shunting type by Na decoration of stacking faults in Si solar cells, Sol. Energ. Mat. Sol. Cells 120, 383 (2014).

[3] D. Lausch et al., Sodium Outdiffusion from Stacking Faults as Root Cause for the Recovery Process of Potential-Induced Degradation (PID), Energy Procedia 55, 486-493 (2014).

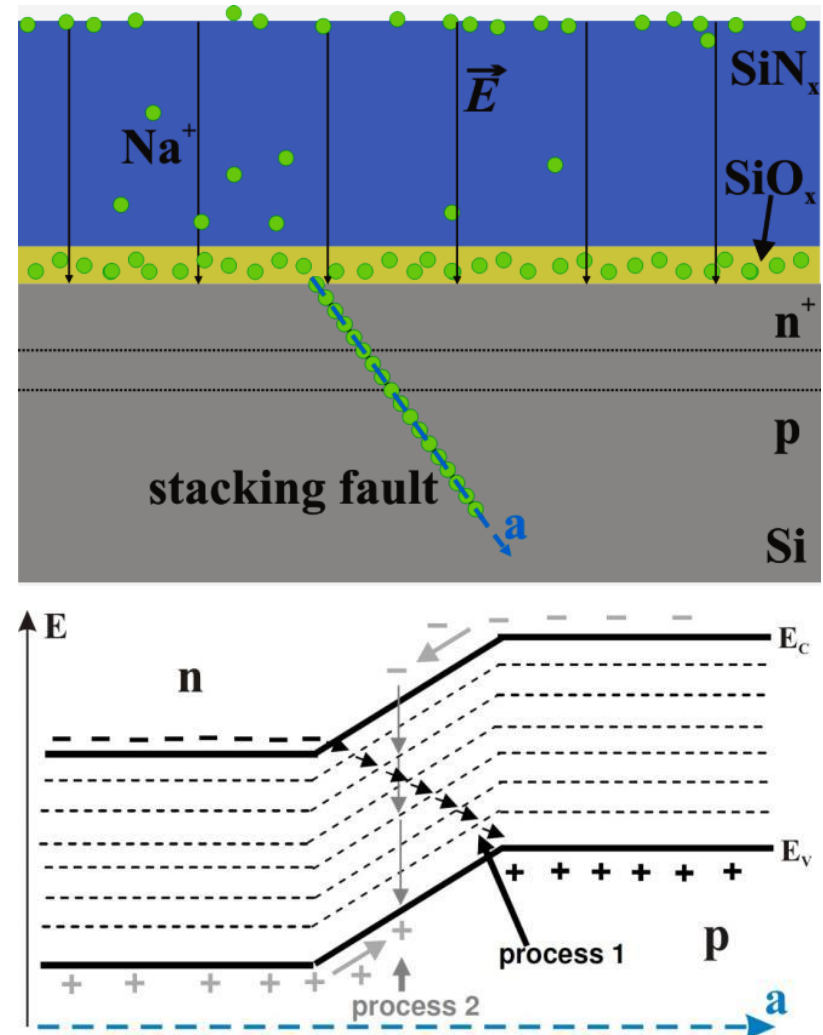
[4] V. Naumann et al., Sodium decoration of PID-s crystal defects after corona induced degradation of bare silicon solar cells, Energy Procedia 77, 397-401 (2015).

5 * independently confirmed by: S. P. Harvey et al., Sodium Accumulation at Potential-Induced Degradation Shunted Areas in Polycrystalline Silicon Modules, IEEE Journal of Photovoltaics 99, 1-6 (2016).

PID-s root cause analysis

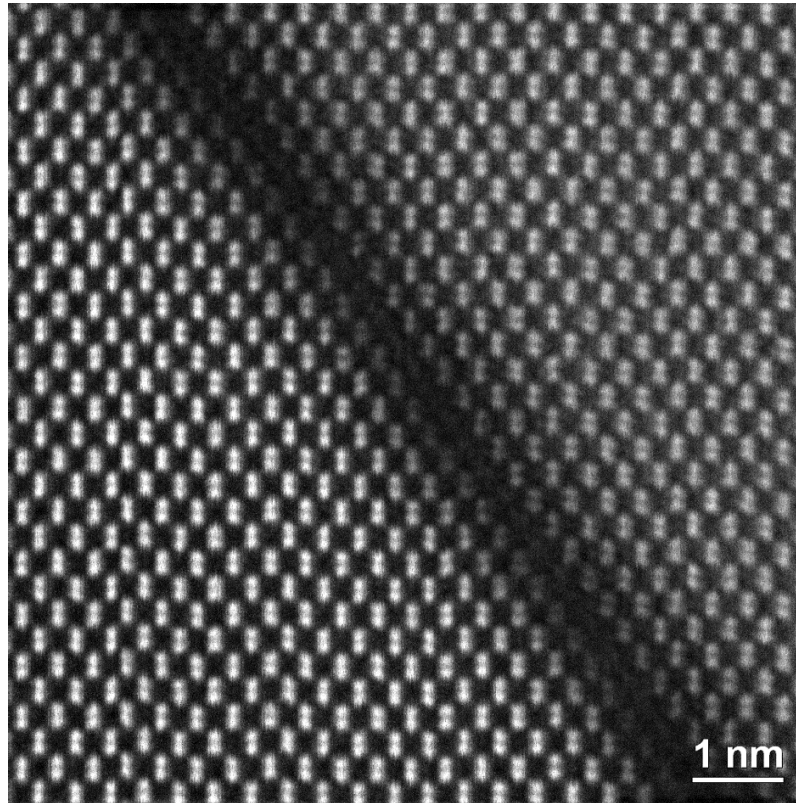
Current model for PID-s [1]

- High field strength causes drift of Na^+ through the SiN_x layer
 - Na accumulates at SiN_x/Si interface and penetrates into stacking faults
-
- Shunting of the p-n junction through defect levels of the highly decorated stacking fault (SF) → shunting, process 1
 - Recombination process via defect states in depletion region → increased J_{02} and $n_2 > 2$, process 2
 - “Most favorable configuration is a SF fully filled with Na atoms...” [2]



PID-s root cause analysis

Scanning Transmission Electron Microscopy (STEM)

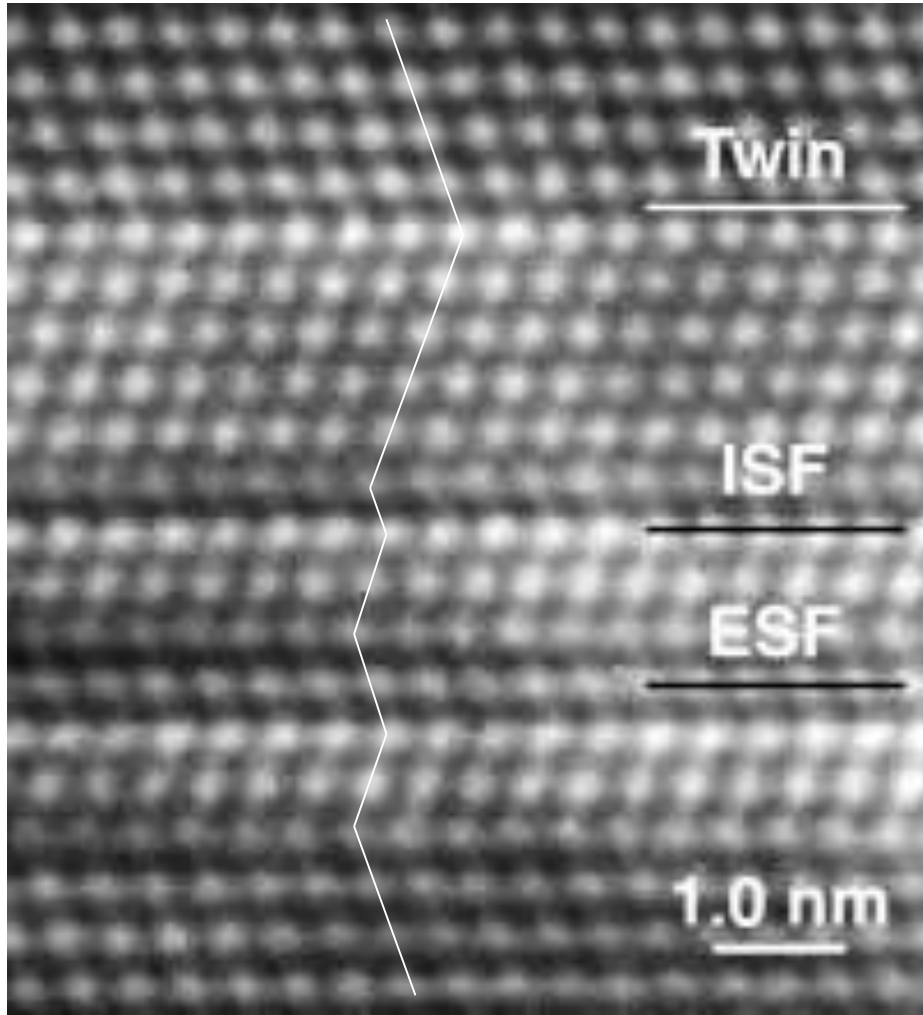


STEM image of a Na decorated planar defect in a {111}-plane

- STEM investigations verify “modified” stacking faults in {111}-planes ^[1]

Type of stacking faults?

Intrinsic vs. extrinsic



Differentiation of stacking faults (SFs) by TEM:

- Intrinsic SF: single fault layer
- Extrinsic SF: double fault layer

TEM-micrograph of SFs and twin boundary in thin film silicon [NREL]

<http://www.nrel.gov/docs/fy00osti/22211.pdf>

Type of stacking faults?

High-res. TEM at PID-s defect

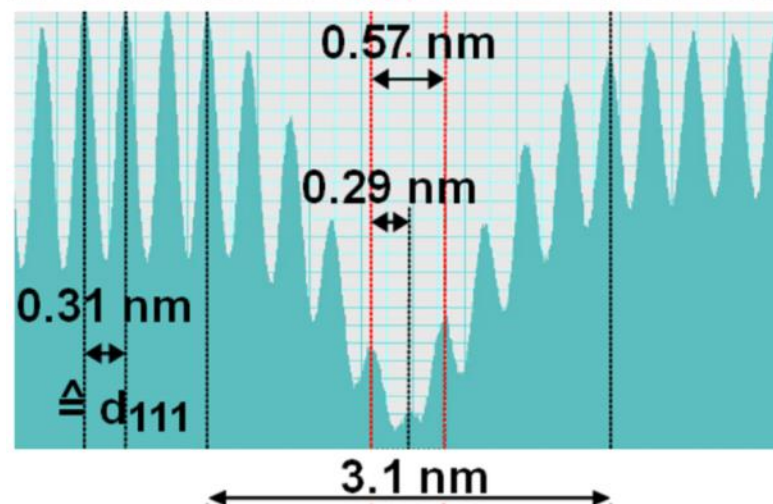
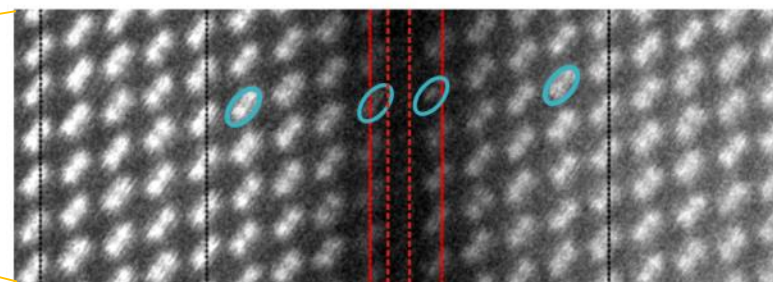
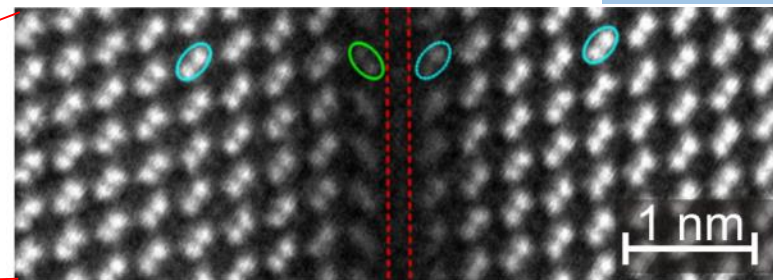
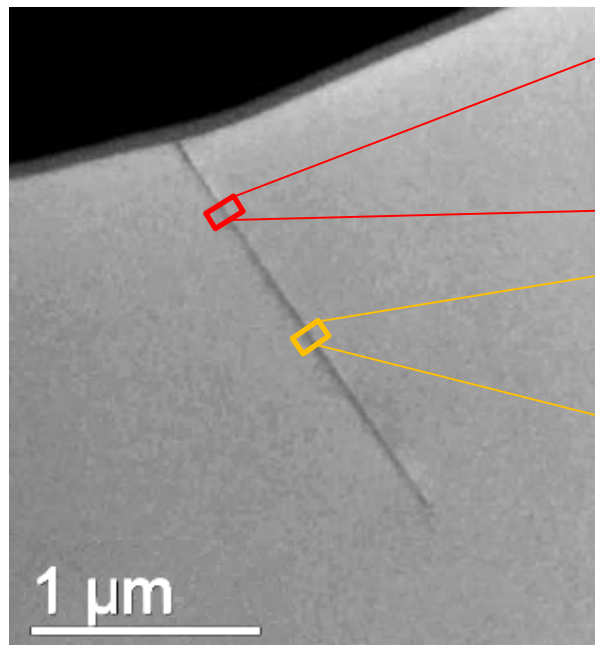


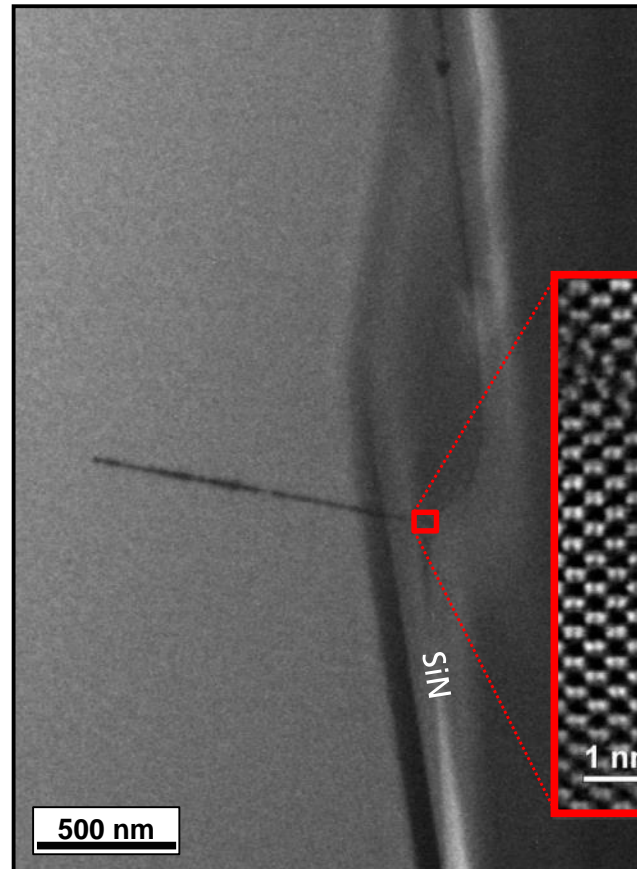
diagram: A. Hähnel

- Low contrast within defect plane
- Regions with differently oriented atom “dumbbells” at the defect
- Width measurements yield widened intrinsic stacking faults

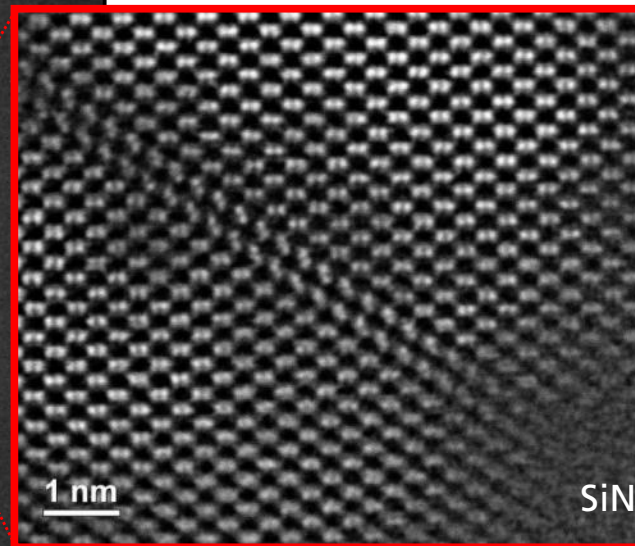
Type of stacking faults?

Partially recovered PID-s defect

- TEM image of an annealed PID-s defect



- Crystal defect without Na decoration remains in Si
- Shallow extrinsic stacking fault



HR-TEM image of recovered defect near the SiN_x interface

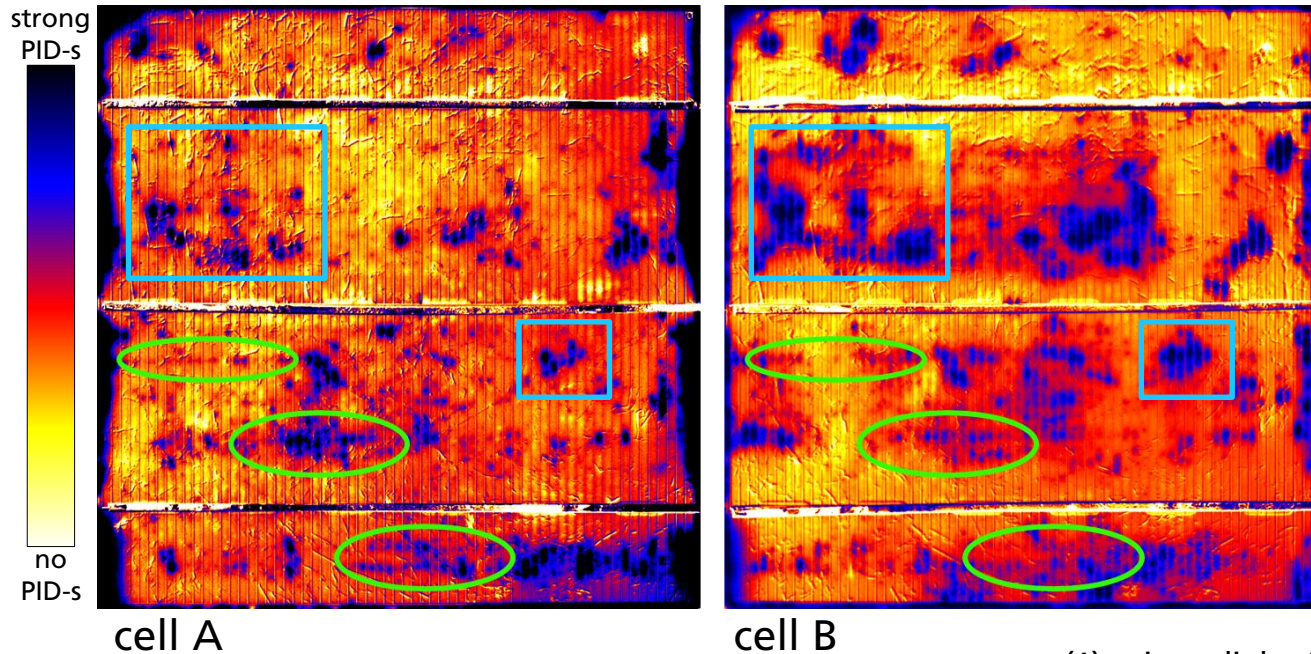
Outline



- PID-s root cause analysis
 - Type of stacking faults
- Quest for PID-s defect precursors
 - 1) Primordial stacking faults
 - 2) Threading dislocations
 - 3) Surface defects
- Conclusion

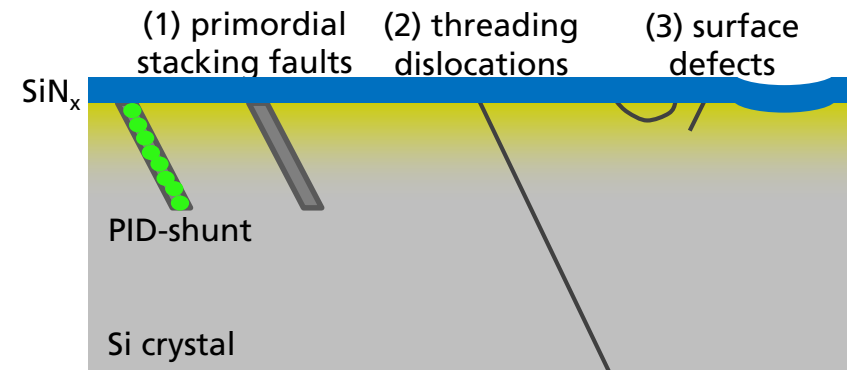
New hints: PID tests at neighboring cells

PID-shunt maps after equal PID tests:



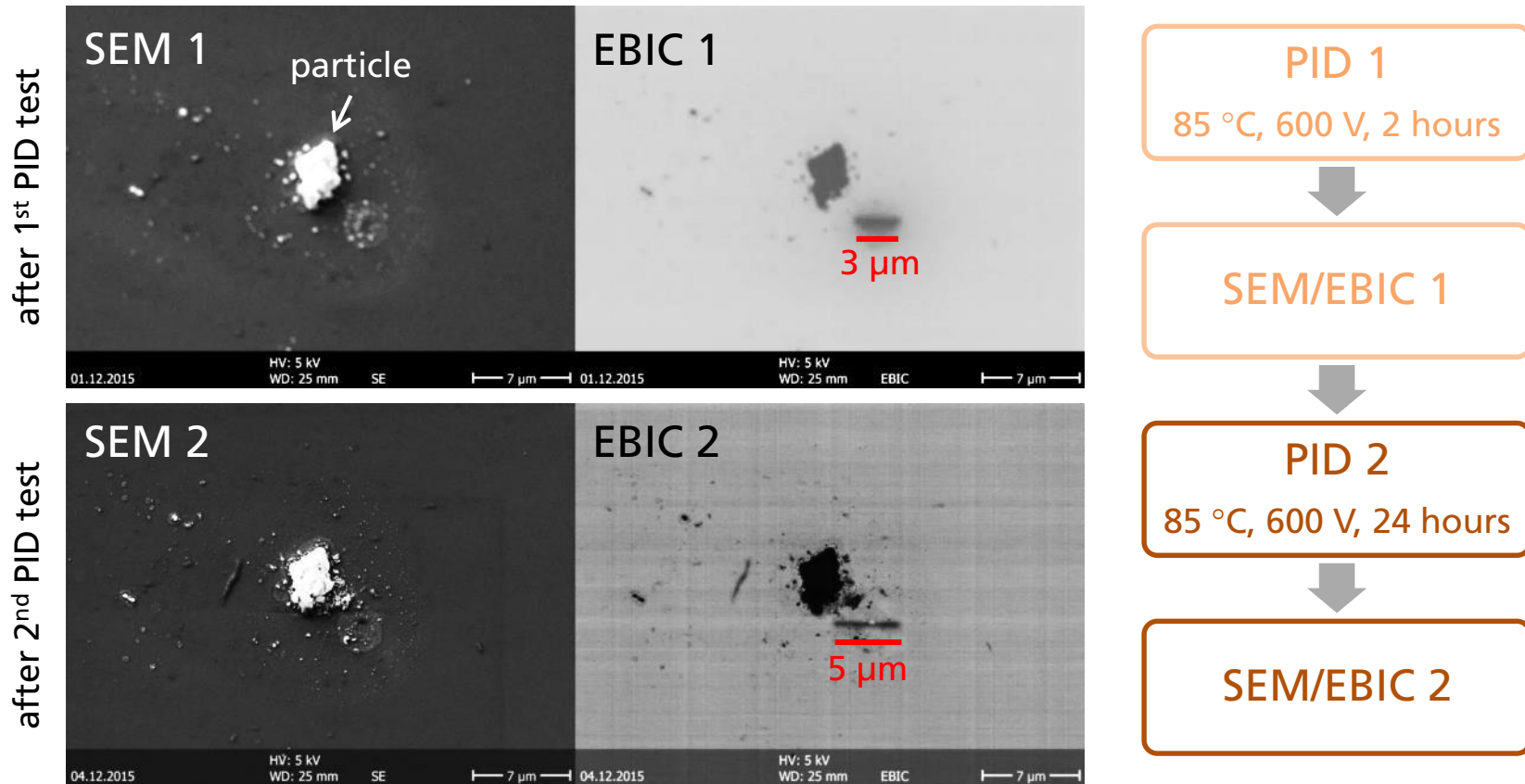
„PID-shunt map“
= $EL_{PID-s} / EL_{initial}$

- PID-shunts exist at same positions
- Indication of material and/or process related defect precursors:



1) Primordial stacking faults?

Growth of PID-s defects during sequential PID stress



- Defects grow in lateral extension under high voltage stress ^[1]
- Indicates that stacking faults do not exist before high voltage stress

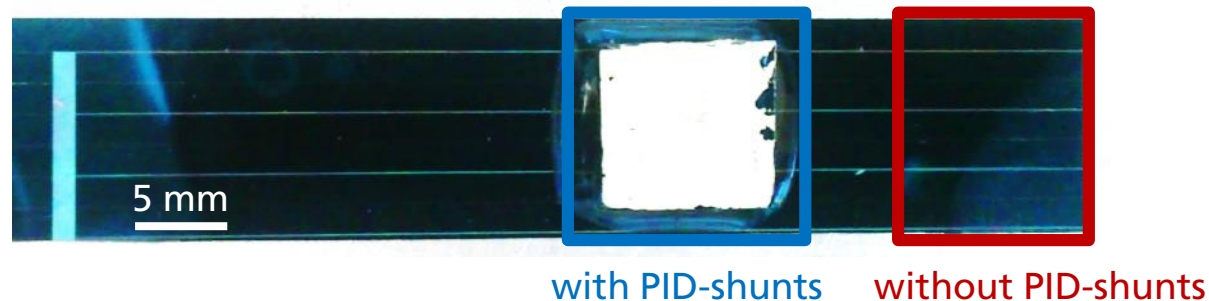
13 [1] V. Naumann et al., Investigations on the formation of stacking fault-like PID-shunts, Energy Procedia 92, 569 - 575 (2016).

1) Primordial stacking faults?

Defect etch for delineation of stacking faults

- Cz p-type solar cell with polished front side and SiN_x
- PIDcon test on $\sim 10 \times 12 \text{ mm}^2$ using EVA/glass-stack (1000 V, 85 °C, 22 hours)

- Two samples:



- SiN_x removal and subsequent defect etch → delineation of stacking faults
- Optical microscopy → image processing → count of linear features in sub-images

1) Primordial stacking faults?

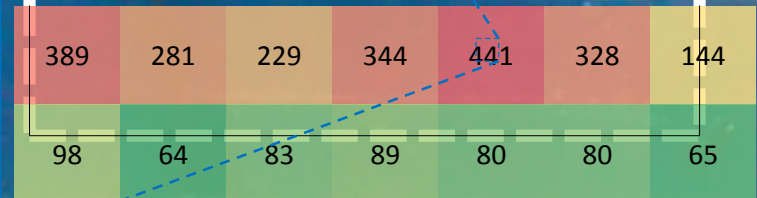
Defect etch for delineation of stacking faults

Linear etch marks = stacking faults

50 μm

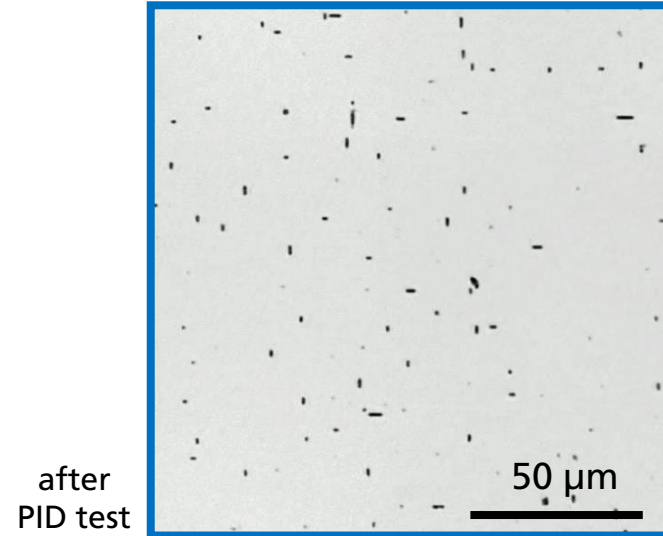
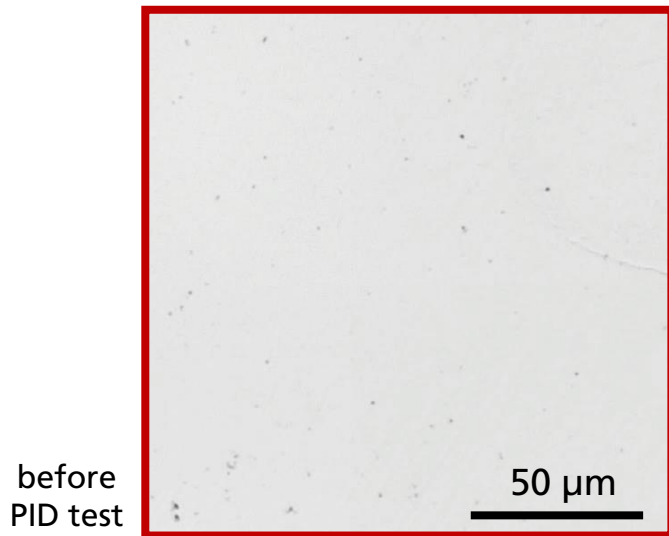
PID test area $\sim 12 \times 10 \text{ mm}^2$

1 mm

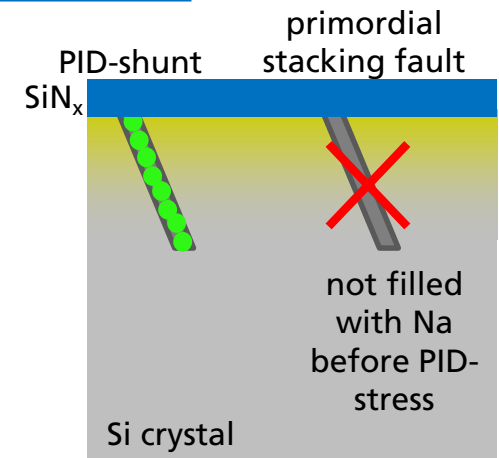


1) Primordial stacking faults?

Defect etch for delineation of stacking faults



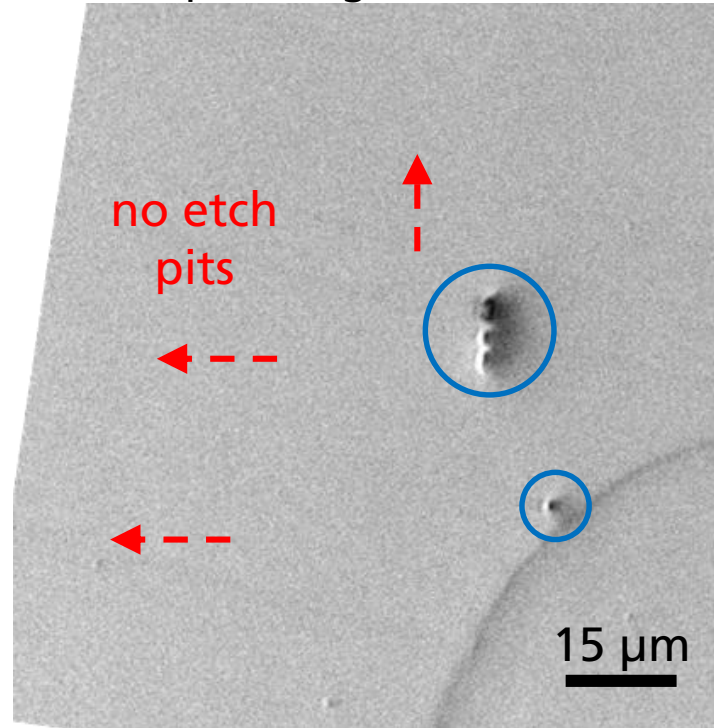
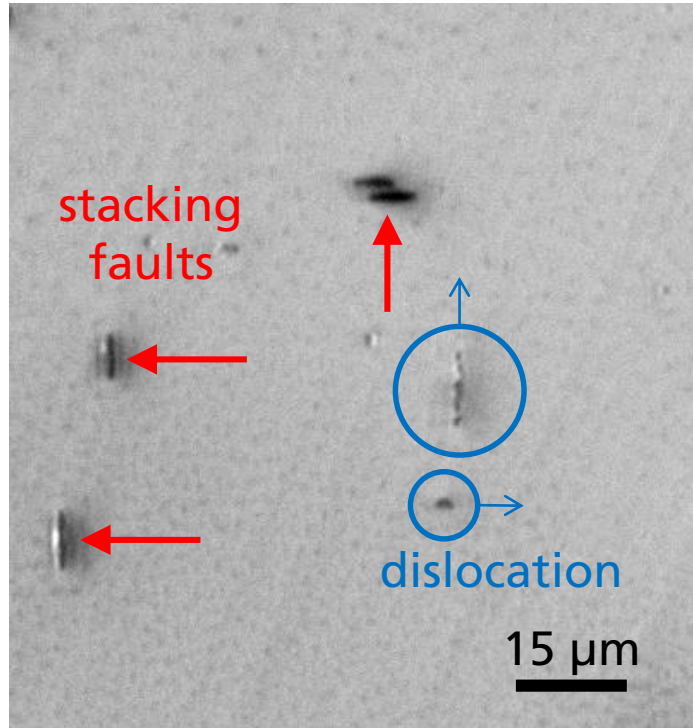
- Etch experiment reveals no stacking faults before high voltage stress, too
- Planar defects (“stacking faults”) don’t exist before high voltage stress



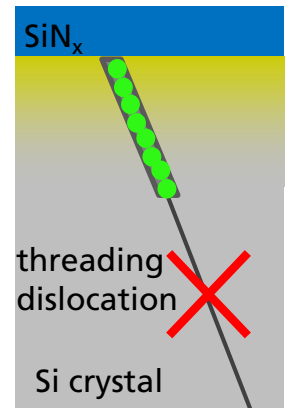
2) Threading dislocations?

Defect etch before and after polish

Removal of SiN + Secco defect etch → Surface polishing + Secco defect etch



- Defect etch before and after $\sim 5\ldots 10\ \mu\text{m}$ surface polish
- Exclusion of threading dislocations as origins for PID-s

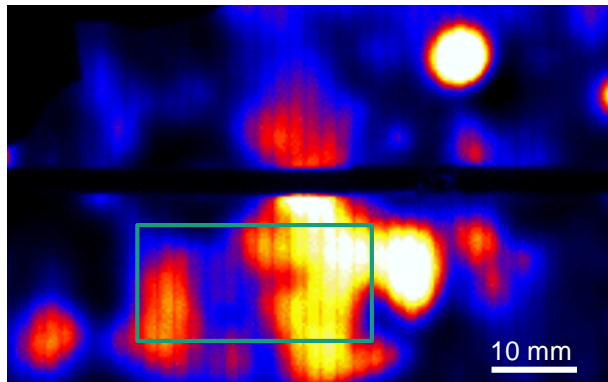


3) Correlation with (micro)structural surface defects?

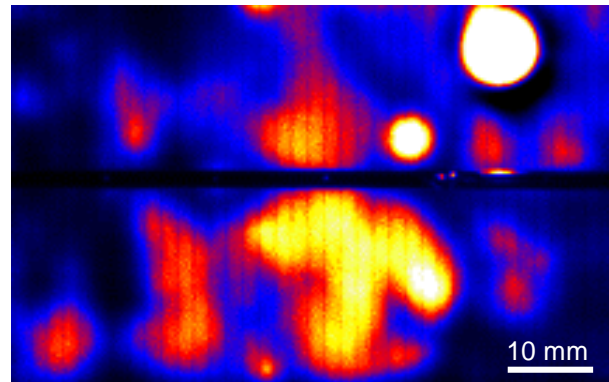
Comparison of PID-s on neighboring cells – macro scale



Lock-in thermography in PID stressed area:

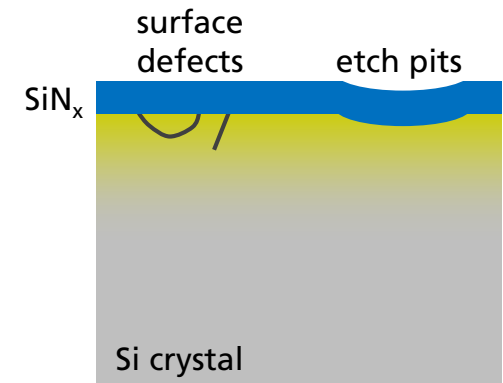


cell 1



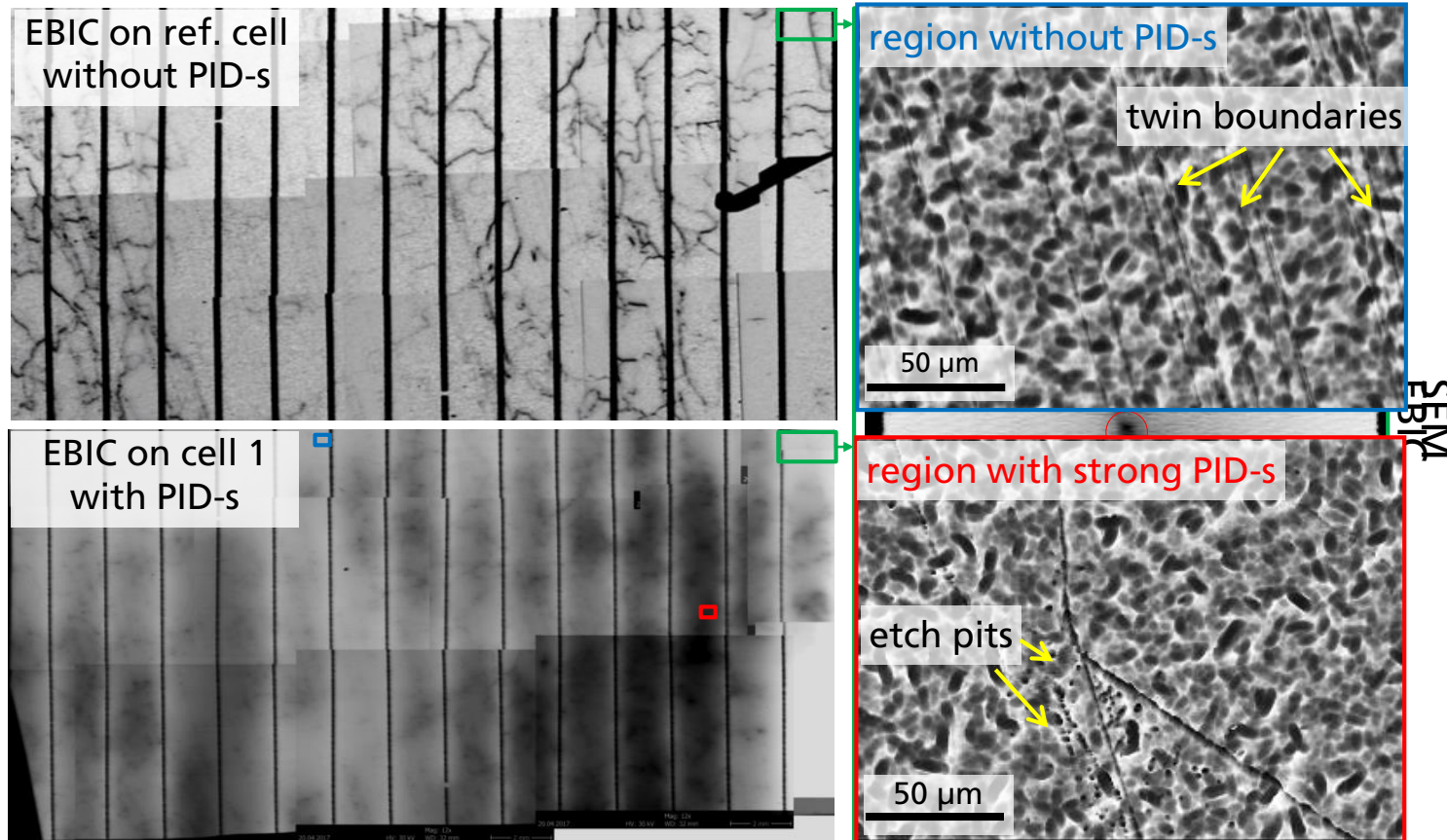
cell 2

- PID-shunts at same positions on a millimeter scale
- Indication for surface defects initially responsible for evolution of PID-s defects



3) Correlation with (micro)structural surface defects?

Comparison of PID-s on neighboring cells – micro scale



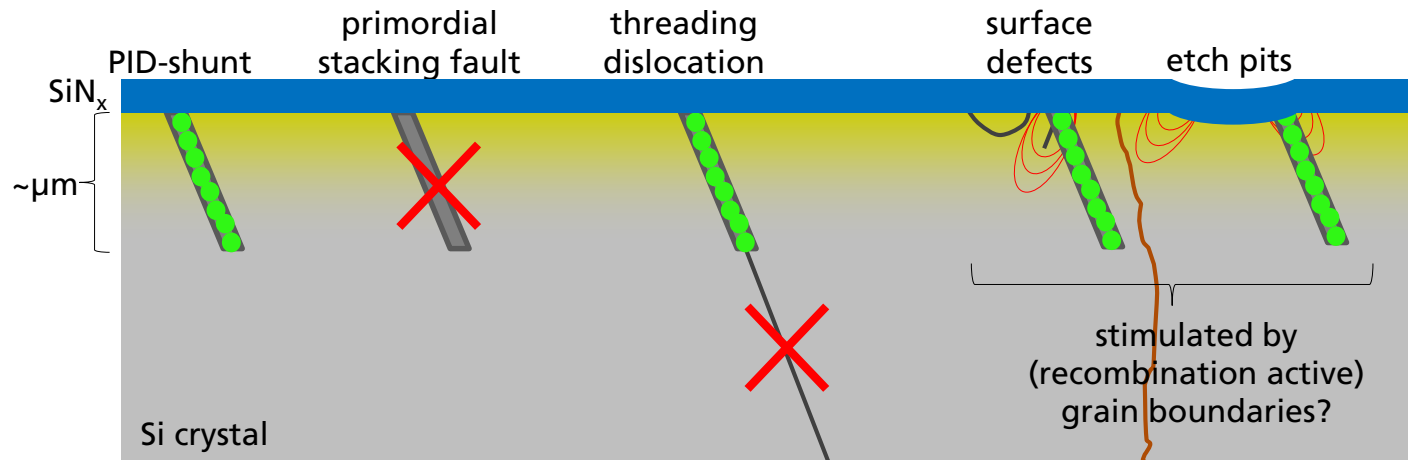
- Higher PID-shunt density at recombination active grain boundaries
- Region with strong PID-s shows less twin boundaries and more etch pits

Conclusion



Model for the origin of PID-shunts:

- No primordial stacking faults
- Threading dislocations not at PID-shunt positions
- Origins of PID-shunts seem to be related to surface defects
- High stress at etch pits (enhanced by recombination active GB) or scratches ^[1]



Stress-related microstructural surface-near defects are points of origin for PID-shunts, i.e. weak points for incorporation of Na, leading to evolution of Na filled planar crystal defects

Thank you!



Acknowledgements:

Carlo Brzuska, Victor Paetzold, Dominik Lausch, Sina Swatek,
Martina Werner, Steffi Göller, Stephan Großer (Fraunhofer CSP)

Angelika Hähnel (MPI Halle, now Fraunhofer IMWS)

Henning Nagel and colleagues (Fraunhofer ISE)



This work is supported by the
Federal Ministry for Economic
Affairs and Energy (BMWi) within
the project “PID-S Solarzellen”
(0325748A).



Federal Ministry
for Economic Affairs
and Energy